

Product / Process Change Notification



N° 2019-004-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Capacity extension for dedicated OptiMOS™ products in PG-TDSON package at Infineon Technologies Wuxi Co., Ltd., China

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **14th March 2019**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0
Chairman of the Supervisory Board: Wolfgang Mayrhuber
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck
Registered Office: Neubiberg Commercial Register
Amtsgericht München HRB 126492

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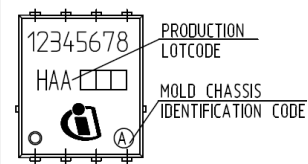

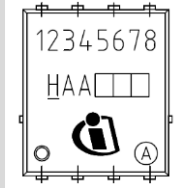
► **Products affected:**

See affected product list 1_cip19004_a

► **Detailed Change Information:**

Subject: - Capacity extension at Infineon Technologies Wuxi Co., Ltd., China (IFX Wuxi) for PG-TDSON package,
- Standardization of mould compound for TDSON-8 package

Reason: Extension of high volume assembly manufacturing capability to cover increasing customer demand and support short term upside demand in a more efficient way.
IFX Wuxi does already mass production in PG-TDSON package.

Description:	<u>Old</u>	<u>New</u>
Assembly and Final Test location:	<ul style="list-style-type: none"> ■ Infineon Technologies Malaysia Sdn. Bhd., Malacca and ■ subcontractor ASE (Weihai) Inc., China 	<ul style="list-style-type: none"> ■ Infineon Technologies Malaysia Sdn. Bhd., Malacca and ■ subcontractor ASE (Weihai) Inc., China and ■ Infineon Technologies Wuxi Co., Ltd., China
Mould compound:	<ul style="list-style-type: none"> ■ Hitachi CEL 1772 	<ul style="list-style-type: none"> ■ Hitachi CEL 9240
Marking on device:	<ul style="list-style-type: none"> ■ No underline on the first letter at the date code fab Malacca  <ul style="list-style-type: none"> ■ No mold chassis identification code at subcontractor ASE 	<ul style="list-style-type: none"> ■ Underlined first letter of date code for assembly fab Wuxi 

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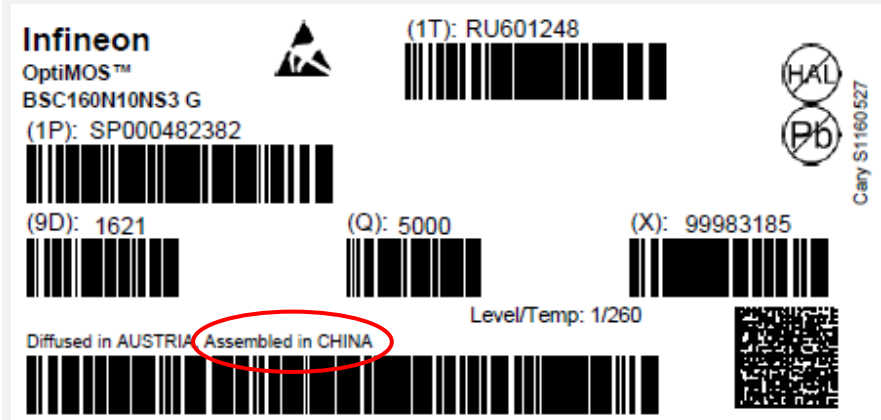


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► Product Identification:

Internal traceability via Baunumber, Lotnumber, date code and marking on device

External traceability via country of assembly on Barcode Product Label (BPL) and marking on device



► Impact of Change:

NO change on electrical, thermal parameters and reliability as proven via product qualification and characterization.

NO change of existing datasheet parameters.

NO change in quality and reliability. Processes are optimized to meet product performance according to already applied Infineon specification.

NO change in package outline dimensions.

► Attachments:

1_cip19004_a Affected Product List
2_cip19004_a Qualification Report



► Time Schedule:

■ Final qualification report:	2019-01-29
■ First samples available:	on request
■ Intended start of delivery:	2019-05-01 or earlier depending on customer approval

If you have any questions, please do not hesitate to contact your local Sales office.